

Title (en)
METHOD OF PRODUCING SEMICONDUCTOR DEVICES

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Application
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DE 3828809 A 19880825

Abstract (en)
[origin: US5096844A] The invention relates to a method in particular for manufacturing bipolar transistors. By applying selective epitaxy methods and by using self-adjusting techniques, the process sequence is shortened and the transistor properties are improved.

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IPC 8 full level
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